

## HT1622/HT1622G RAM Mapping 32×8 LCD Controller for I/O MCU

# **PATENTED** PAT No. : 099352

### Features

- Operating voltage: 2.7V~5.2V
- Built-in RC oscillator
- 1/4 bias, 1/8 duty, frame frequency is 64Hz
- Max. 32×8 patterns, 8 commons, 32 segments
- Built-in internal resistor type bias generator
- 3-wire serial interface
- 8 kinds of time base or WDT selection
- Time base or WDT overflow output
- Built-in LCD display RAM

- R/W address auto increment
- Two selectable buzzer frequencies (2kHz or 4kHz)
- Power down command reduces power consumption
- Software configuration feature
- Data mode and Command mode instructions
- Three data accessing modes
- VLCD pin to adjust LCD operating voltage
- 44/52/64-pin LQFP packages
- HT1622G: Gold bumped chip

### **General Description**

HT1622 is a peripheral device specially designed for I/O type MCU used to expand the display capability. The max. display segment of the device are 256 patterns (32×8). It also supports serial interface, buzzer sound, Watchdog Timer or time base timer functions. The HT1622 is a memory mapping and multi-function LCD

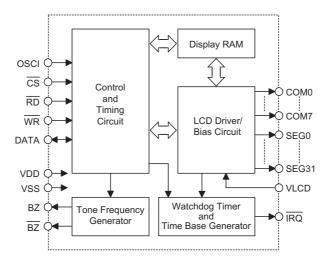
controller. The software configuration feature of the HT1622 make it suitable for multiple LCD applications including LCD modules and display subsystems. Only three lines are required for the interface between the host controller and the HT1622. The HT162X series have many kinds of products that match various applications.

HT162X	HT1620	HT1621	HT1622	HT16220	HT1623	HT1625	HT1626
СОМ	4	4	8	8	8	8	16
SEG	32	32	32	32	48	64	48
Built-in Osc.		$\checkmark$	$\checkmark$		$\checkmark$	$\checkmark$	
Crystal Osc.	$\checkmark$	$\checkmark$		$\checkmark$	$\checkmark$	$\checkmark$	

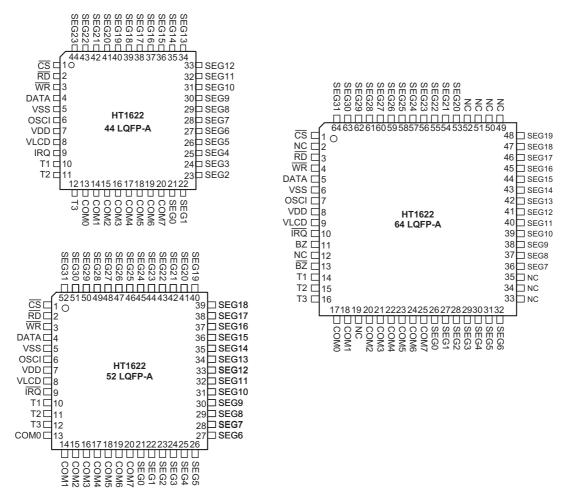
### **Selection Table**



### **Block Diagram**

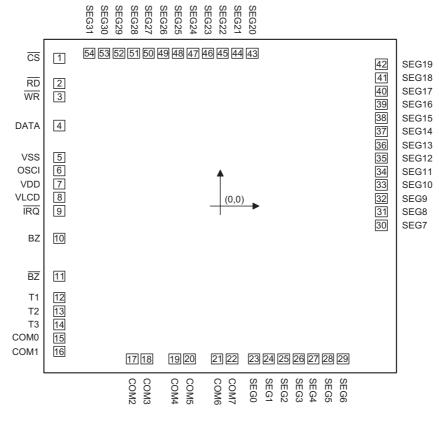


### **Pin Assignment**





### **Pad Assignment**



Chip size:  $94 \times 98$  (mil)<sup>2</sup>

Bump height:  $18\mu m \pm 3\mu m$ 

Min. Bump spacing: 23.102µm

Bump size:  $76 \times 76 \mu m^2$ 

\* The IC substrate should be connected to VDD in the PCB layout artwork.



## HT1622/HT1622G

### **Pad Coordinates**

Pad Coordina	ates				Unit: µm
Pad No.	Х	Y	Pad No.	Х	Y
1	-1077.075	1090.589	28	721.077	-1129.575
2	-1077.075	905.211	29	820.095	-1129.575
3	-1077.075	806.109	30	1076.900	-141.904
4	-1077.075	594.542	31	1076.900	-42.885
5	-1077.037	359.680	32	1076.900	56.215
6	-1077.075	260.745	33	1076.900	155.234
7	-1077.037	162.710	34	1076.900	254.335
8	-1077.075	63.734	35	1076.900	353.354
9	-1077.075	-34.789	36	1076.900	452.456
10	-1077.075	-238.247	37	1076.900	551.474
11	-1077.075	-519.705	38	1076.900	650.576
12	-1077.075	-677.315	39	1076.900	749.594
13	-1077.075	-776.416	40	1076.900	848.695
14	-1077.075	-875.435	41	1076.900	947.714
15	-1077.075	-974.536	42	1076.900	1046.816
16	-1077.075	-1073.554	43	213.669	1127.150
17	-589.281	-1129.575	44	114.650	1127.150
18	-490.179	-1129.575	45	15.550	1127.150
19	-304.799	-1129.575	46	-83.469	1127.150
20	-205.699	-1129.575	47	-182.570	1127.150
21	-20.319	-1129.575	48	-281.590	1127.150
22	78.736	-1129.575	49	-380.690	1127.150
23	225.736	-1129.575	50	-479.710	1127.150
24	324.836	-1129.575	51	-578.810	1127.150
25	423.856	-1129.575	52	-677.829	1127.150
26	522.957	-1129.575	53	-776.931	1127.150
27	621.975	-1129.575	54	-875.949	1127.150

## **Pad Description**

Pad No.	Pad Name	I/O	Description
Pau NO.	Fau Name	1/0	·
1	cs	I	Chip selection input with Pull-high resistor. When the CS is logic high, the data and command read from or written to the HT1622 are disabled. The serial interface circuit is also reset. But if $\overline{CS}$ is at logic low level and is input to the $\overline{CS}$ pad, the data and command transmission between the host controller and the HT1622 are all enabled.
2	RD	Ι	READ clock input with Pull-high resistor. Data in the RAM of the HT1622 are clocked out on the falling edge of the $\overline{RD}$ signal. The clocked out data will appear on the data line. The host controller can use the next rising edge to latch the clocked out data.
3	WR	I	WRITE clock input with Pull-high resistor. Data on the DATA line are latched into the HT1622 on the rising edge of the $\overline{\rm WR}$ signal.
4	DATA	I/O	Serial data input or output with Pull-high resistor
5	VSS		Negative power supply, ground
6	OSCI	I	If the system clock comes from an external clock source, the external clock source should be connected to the OSCI pad.
7	VDD	_	Positive power supply
8	VLCD	I	LCD operating voltage input pad
9	ĪRQ	0	Time base or Watchdog Timer overflow flag, NMOS open drain output
10, 11	BZ, BZ	0	2kHz or 4kHz tone frequency output pair
12~14	T1~T3	I	Not connected
15~22	COM0~COM7	0	LCD common outputs
23~54	SEG0~SEG31	0	LCD segment outputs



### **Absolute Maximum Ratings**

Supply VoltageV_SS=0.3V to V_SS+5.5V	Storage Temperature50°C to 125°C
Input VoltageV_SS-0.3V to V_DD+0.3V	Operating Temperature40°C to 85°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

### **D.C. Characteristics**

#### Ta=25°C

Cumb al	Devenueter		Test Conditions	Min	_	Mari	11
Symbol	Parameter	V <sub>DD</sub>	Conditions	Min.	Тур.	Max.	Unit
V <sub>DD</sub>	Operating Voltage	_	_	2.7	_	5.2	V
	Operating Current		No load/LCD ON	_	80	210	μA
I <sub>DD1</sub>	Operating Current	5V	On-chip RC oscillator	_	135	415	μA
I	Operating Current	3V	No load/LCD OFF	_	8	30	μA
I <sub>DD2</sub>	Operating Current	5V	On-chip RC oscillator	_	20	55	μA
l	Standby Current	3V	No load Dower Down Mode	_	1	8	μA
I <sub>STB</sub>	Standby Current	5V	No load, Power Down Mode	_	2	16	μA
V <sub>IL</sub>	Input Low Voltage	3V	DATA, $\overline{WR}$ , $\overline{CS}$ , $\overline{RD}$	0		0.6	V
VIL	Input Low Voltage		DATA, WR, CS, RD	0		1.0	V
VIH	Input Lligh Voltage	3V	DATA, WR, CS, RD	2.4		3.0	V
VIН	Input High Voltage	5V	DATA, WR, CS, RD	4.0		5.0	V
I		3V	V <sub>OL</sub> =0.3V	0.9	1.8		mA
I <sub>OL1</sub>	BZ, BZ, IRQ	5V	V <sub>OL</sub> =0.5V	1.7	3.0	_	mA
I	BZ, BZ	3V	V <sub>OH</sub> =2.7V	-0.9	-1.8		mA
I <sub>OH1</sub>	DZ, DZ	5V	V <sub>OH</sub> =4.5V	-1.7	-3.0		mA
lava.	DATA		V <sub>OL</sub> =0.3V	200	450		μA
I <sub>OL2</sub>	DATA	5V	V <sub>OL</sub> =0.5V	250	500		μA
I	DATA		V <sub>OH</sub> =2.7V	-200	-450		μA
I <sub>OH2</sub>	DATA	5V	V <sub>OH</sub> =4.5V	-250	-500		μA
1	LCD Common Sink Current	3V	V <sub>OL</sub> =0.3V	15	40		μA
I <sub>OL3</sub>	LCD Common Sink Current	5V	V <sub>OL</sub> =0.5V	100	200		μA
I	LCD Common Source Current	3V	V <sub>OH</sub> =2.7V	-15	-30		μA
I <sub>OH3</sub>	LCD Common Source Current	5V	V <sub>OH</sub> =4.5V	-45	-90		μA
I	LCD Segment Sink Current	3V	V <sub>OL</sub> =0.3V	15	30		μA
I <sub>OL4</sub>	LCD Segment Sink Current	5V	V <sub>OL</sub> =0.5V	70	150		μA
	LCD Segment Source Current	3V	V <sub>OH</sub> =2.7V	-6	-13		μA
I <sub>OH4</sub>	LCD Segment Source Current	5V	V <sub>OH</sub> =4.5V	-20	-40	_	μA
D	Dull bigh Desister	3V		100	200	300	kΩ
R <sub>PH</sub>	Pull-high Resistor	5V	DATA, WR, CS, RD	50	100	150	kΩ



Ta=25°C

#### **Test Conditions** Symbol Parameter Min. Тур. Max. Unit $V_{\text{DD}}$ Conditions 3V On-chip RC oscillator 24 32 40 kHz 5V f<sub>SYS</sub> System Clock External clock source 32768 Hz \_\_\_\_ \_\_\_\_ \_\_\_\_ 3V On-chip RC oscillator 48 80 64 Ηz 5V $\mathsf{f}_{\mathsf{LCD}}$ LCD Frame Frequency External clock source 64 Ηz \_\_\_\_ LCD Common Period n: Number of COM n/f<sub>LCD</sub> t<sub>COM</sub> \_\_\_\_ \_\_\_\_ sec 3V 4 150 kHz \_\_\_\_ f<sub>CLK1</sub> Serial Data Clock (WR pin) Duty cycle 50% 5V 4 300 kHz \_\_\_\_ 75 kHz 3V \_\_\_\_ \_\_\_\_ Serial Data Clock (RD pin) f<sub>CLK2</sub> Duty cycle 50% 5V 150 kHz Serial Interface Reset Pulse Width $\overline{\text{CS}}$ 500 t<sub>CS</sub> 600 ns (Figure 3) Write mode 3.34 125 3V μS Read mode 6.67 WR, RD Input Pulse Width (Figure 1) t<sub>CLK</sub> Write mode 1.67 125 5V μs Read mode 3.34 \_\_\_\_ \_\_\_\_ Rise/Fall Time Serial Data Clock Width t<sub>r</sub>, t<sub>f</sub> 120 160 ns (Figure 1) Setup Time for DATA to $\overline{\mathsf{WR}},\,\overline{\mathsf{RD}}$ Clock 60 120 t<sub>su</sub> ns Width (Figure 2) Hold Time for DATA to WR, RD, Clock t<sub>h</sub> 500 600 ns Width (Figure 2) Setup Time for $\overline{CS}$ to $\overline{WR}$ , $\overline{RD}$ Clock 500 600 t<sub>su1</sub> ns Width (Figure 3) Hold Time for $\overline{CS}$ to $\overline{WR}$ , $\overline{RD}$ Clock t<sub>h1</sub> 700 800 ns Width (Figure 3) 3V Tone Frequency (2kHz) On-chip RC oscillator 1.5 20 2.5 kHz 5V **f**TONE 3V Tone Frequency (4kHz) On-chip RC oscillator 3 4 5 kHz 5V V<sub>DD</sub> OFF Times (Figure 4) VDD drop down to 0V 20 tOFF \_\_\_\_ ms t<sub>SR</sub> V<sub>DD</sub> Rising Slew Rate (Figure 4) 0.05 V/ms \_\_\_\_ \_ Delay Time after Reset (Figure 4) 1 \_\_\_\_ ms **t**<sub>RSTD</sub>

### A.C. Characteristics

Note: 1. If the conditions of Power-on Reset timing are not satisfied in power On/Off sequence, the internal Power-on Reset (POR) circuit will not operate normally.

2. If the VDD drops below the minimum voltage of operating voltage spec. during operating, the conditions of Power-on Reset timing must be satisfied also. That is, the VDD must drop to 0V and keep at 0V for 20ms (min.) before rising to the normal operating voltage.

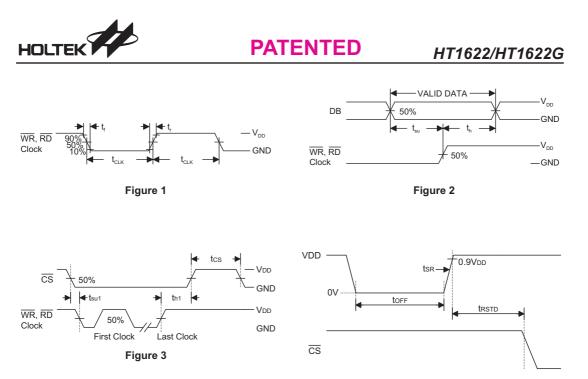


Figure 4. Power-on Reset Timing

#### **RC Oscillator Frequency Deviation**

Operating Temperature	-40°C	0°C	25°C	70°C	75°C	80°C	85°C
Average Deviation	19.85%	2.98%	0	-21.14%	-22.50%	-23.82%	-25.35%



### **Functional Description**

#### **Display Memory – RAM Structure**

The static display RAM is organized into 64×4 bits and stores the display data. The contents of the RAM are directly mapped to the contents of the LCD driver. Data in the RAM can be accessed by the READ, WRITE and READ-MODIFY-WRITE commands. The following is a mapping from the RAM to the LCD patterns.

#### Time Base and Watchdog Timer (WDT)

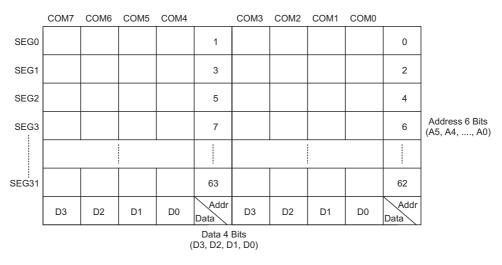
The time base generator and WDT share the same divided ( $\pm$ 256) counter. TIMER DIS/EN/CLR, WDT DIS/EN/CLR and IRQ EN/DIS are independent from each other. Once the WDT time-out occurs, the IRQ pin will

remain at logic low level until the CLR WDT or the  $\overline{\rm IRQ}$  DIS command is issued.

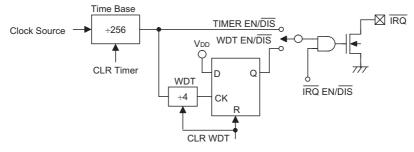
If an external clock is selected as the source of system frequency, the SYS DIS command turns out invalid and the power down mode fails to be carried out until the external clock source is removed.

#### **Buzzer Tone Output**

A simple tone generator is implemented in the HT1622. The tone generator can output a pair of differential driving signals on the BZ and  $\overline{\text{BZ}}$  which are used to generate a single tone.







Timer and WDT Configurations





#### **Command Format**

The HT1622 can be configured by the software setting. There are two mode commands to configure the HT1622 resource and to transfer the LCD display data.

The following are the data mode ID and the command mode ID:

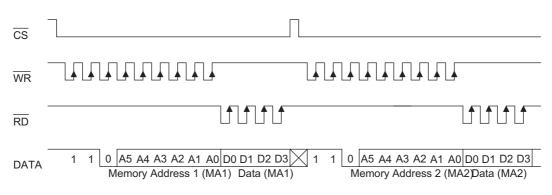
Operation	Mode	ID
READ	Data	110
WRITE	Data	101
READ-MODIFY-WRITE	Data	101
COMMAND	Command	100

If successive commands have been issued, the command mode ID can be omitted. While the system is operating in a non-successive command or a non-successive address data mode, the  $\overline{\text{CS}}$  pin should be set to "1" and the previous operation mode will be reset also. The  $\overline{\text{CS}}$  pin returns to "0", a new operation mode ID should be issued first.

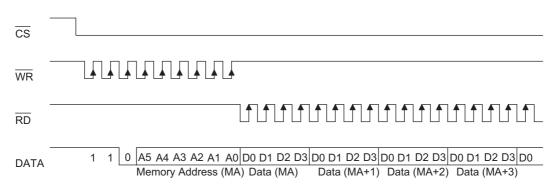
Name	Command Code	Function
TONE OFF	0000-1000-X	Turn-off tone output
TONE 4K	010X-XXXX-X	Turn-on tone output, tone frequency is 4kHz
TONE 2K	0110-XXXX-X	Turn-on tone output, tone frequency is 2kHz

### **Timing Diagrams**

READ Mode (Command Code : 1 1 0)



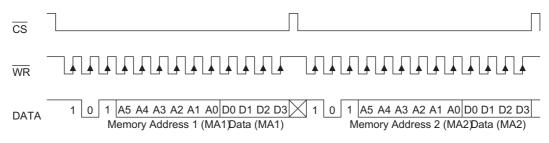
#### **READ Mode (Successive Address Reading)**



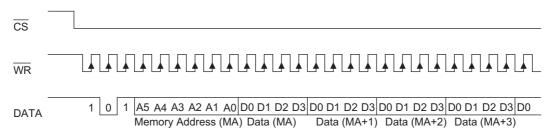
HOLTEK
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HT1622/HT1622G

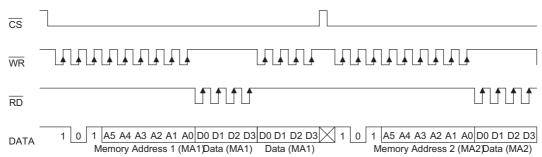
WRITE Mode (Command Code : 1 0 1)



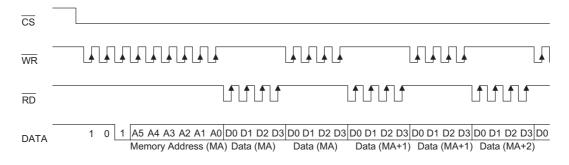
#### WRITE Mode (Successive Address Writing)



### READ-MODIFY-WRITE Mode (Command Code : 1 0 1)



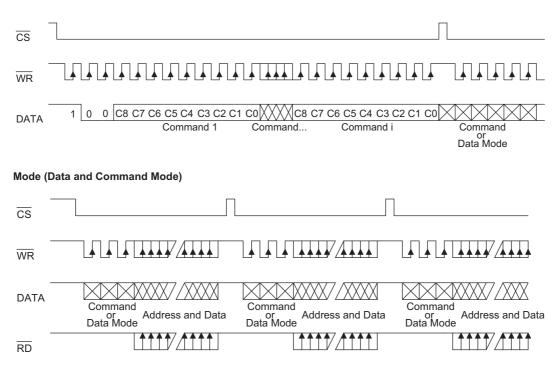
#### READ-MODIFY-WRITE Mode (Successive Address Accessing)





HT1622/HT1622G

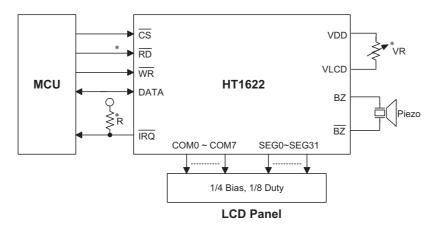
Command Mode (Command Code : 1 0 0)







### **Application Circuits**



Note: The connection of IRQ and RD pin can be selected depending on the requirement of the MCU.
The voltage applied to V<sub>LCD</sub> pin must be equal to or lower than V<sub>DD</sub>.
Adjust VR to fit user's LCD panel display voltage (V<sub>LCD</sub>).
Adjust R (external pull-high resistance) to fit user's time base clock.

### **Command Summary**

Name	ID	Command Code	D/C	Function	Def.
READ	110	A5A4A3A2A1A0D0D1D2D3	D	Read data from the RAM	
WRITE	101	A5A4A3A2A1A0D0D1D2D3	D	Write data to the RAM	
READ-MODIFY- WRITE	101	A5A4A3A2A1A0D0D1D2D3	D	Read and Write data to the RAM	
SYS DIS	100	0000-0000-X	С	Turn off both system oscillator and LCD bias generator	Yes
SYS EN	100	0000-0001-X	С	Turn on system oscillator	
LCD OFF	100	0000-0010-X	С	Turn off LCD display	Yes
LCD ON	100	0000-0011-X	С	Turn on LCD display	
TIMER DIS	100	0000-0100-X	С	Disable time base output	Yes
WDT DIS	100	0000-0101-X	С	Disable WDT time-out flag output	Yes
TIMER EN	100	0000-0110-X	С	Enable time base output	
WDT EN	100	0000-0111-X	С	Enable WDT time-out flag output	
TONE OFF	100	0000-1000-X	С	Turn off tone outputs	Yes
CLR TIMER	100	0000-1101-X	С	Clear the contents of the time base generator	
CLR WDT	100	0000-1111-X	С	Clear the contents of WDT stage	
RC 32K	100	0001-10XX-X	С	System clock source, on-chip RC oscillator	Yes
EXT 32K	100	0001-11XX-X	С	System clock source, external clock source	
TONE 4K	100	010X-XXXX-X	С	Tone frequency output: 4kHz	
TONE 2K	100	0110-XXXX-X	С	Tone frequency output: 2kHz	
IRQ DIS	100	100X-0XXX-X	С	Disable IRQ output	Yes
ÎRQ EN	100	100X-1XXX-X	С	Enable IRQ output	





Name	ID	Command Code	D/C	Function	Def.
F1	100	101X-0000-X	С	Time base clock output: 1Hz The WDT time-out flag after: 4s	
F2	100	101X-0001-X	С	Time base clock output: 2Hz The WDT time-out flag after: 2s	
F4	100	101X-0010-X	С	Time base clock output: 4Hz The WDT time-out flag after: 1s	
F8	100	101X-0011-X	С	Time base clock output: 8Hz The WDT time-out flag after: 1/2s	
F16	100	101X-0100-X	С	Time base clock output: 16Hz The WDT time-out flag after: 1/4s	
F32	100	101X-0101-X	С	Time base clock output: 32Hz The WDT time-out flag after: 1/8s	
F64	100	101X-0110-X	С	Time base clock output: 64Hz The WDT time-out flag after: 1/16s	
F128	100	101X-0111-X	С	Time base clock output: 128Hz The WDT time-out flag after: 1/32s	Yes
TEST	100	1110-0000-X	С	Test mode, user don't use.	
NORMAL	100	1110-0011-X	С	Normal mode	Yes

Note: X : Don't care

A5~A0 : RAM address

D3~D0 : RAM data

D/C : Data/Command mode

Def. : Power on reset default

All the bold forms, namely **1 1 0**, **1 0 1**, and **1 0 0**, are mode commands. Of these, **1 0 0** indicates the command mode ID. If successive commands have been issued, the command mode ID except for the first command will be omitted. The source of the tone frequency and of the time base or WDT clock frequency can be derived from an on-chip 32kHz RC oscillator or an external 32768Hz clock. Calculation of the frequency is based on the system frequency sources as stated above. It is recommended that the host controller should initialize the HT1622 after power on reset, for power on reset may fail, which in turn leads to the malfunctioning of the HT1622.



### Package Information

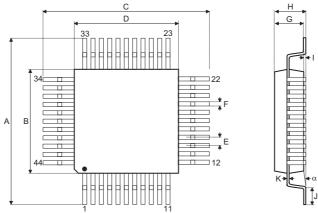
Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the <u>Holtek website</u> for the latest version of the package information.

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Further Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- Packing Meterials Information
- Carton information



### 44-pin LQFP (10mm×10mm) (FP2.0mm) Outline Dimensions

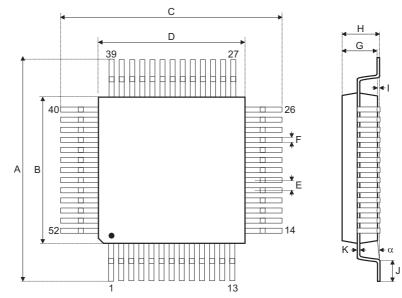


Symbol		Dimensions in inch	
Symbol	Min.	Nom.	Max.
А	_	0.472 BSC	_
В		0.394 BSC	
С		0.472 BSC	_
D		0.394 BSC	_
E		0.032 BSC	_
F	0.012	0.015	0.018
G	0.053	0.055	0.057
Н	_	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
К	0.004	_	0.008
α	0°		<b>7</b> °

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
А	_	12.00 BSC	—
В		10.00 BSC	
С	_	12.00 BSC	—
D		10.00 BSC	
E		0.80 BSC	—
F	0.30	0.37	0.45
G	1.35	1.40	1.45
Н	_	_	1.60
I	0.05	_	0.15
J	0.45	0.60	0.75
К	0.09		0.20
α	0°		<b>7</b> °



### 52-pin LQFP (14mm×14mm) Outline Dimensions

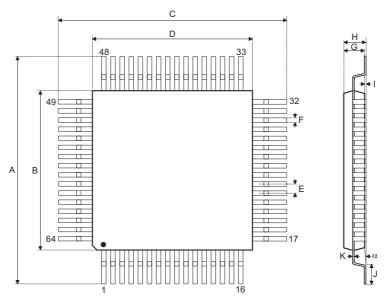


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.622	0.630	0.638
В	0.547	0.551	0.555
С	0.622	0.630	0.638
D	0.547	0.551	0.555
E		0.039 BSC	_
F	0.015		0.019
G	0.053	0.055	0.057
Н			0.063
I	0.002		0.008
J	0.018		0.030
К	0.005	_	0.007
α	0°		<b>7</b> °

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	15.80	16.00	16.20
В	13.90	14.00	14.10
С	15.80	16.00	16.20
D	13.90	14.00	14.10
E		1.0 BSC	_
F	0.39		0.48
G	1.35	1.40	1.45
Н			1.60
1	0.05		0.20
J	0.45		0.75
К	0.13		0.18
α	0°	—	<b>7</b> °



### 64-pin LQFP (7mm×7mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A		0.354 BSC	—
В		0.276 BSC	_
С		0.354 BSC	_
D		0.276 BSC	
E	_	0.020 BSC	_
F	0.005	0.007	0.009
G	0.053	0.055	0.057
Н	—	_	0.063
I	0.002		0.006
J	0.018	0.024	0.030
К	0.004		0.008
α	0°	—	<b>7</b> °

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	_	9.00 BSC	—
В		7.00 BSC	—
С	_	9.00 BSC	—
D		7.00 BSC	_
E		0.40 BSC	—
F	0.13	0.18	0.23
G	1.35	1.40	1.45
Н	_	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
К	0.09	—	0.20
α	0°		<b>7</b> °



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